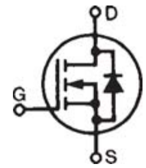
IXYS

HiPerFET™ Power MOSFET Q2-Class

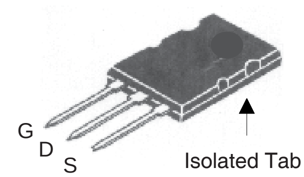
IXFL38N100Q2

V_{DSS} = 1000V
I_{D25} = 29A
$R_{DS(on)}$ ≤ 280mΩ
t_{rr} ≤ 300ns

N-Channel Enhancement Mode
Avalanche Rated, Low Q_g, Low Intrinsic R_G
High dV/dt, Low t_{rr}



ISOPLUS264™(IXFL)



G = Gate D = Drain
S = Source

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	1000	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	1000	V
V_{GSS}	Continuous	± 30	V
V_{GSM}	Transient	± 40	V
I_{D25}	T_C = 25°C	29	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	152	A
I_A	T_C = 25°C	38	A
E_{AS}	T_C = 25°C	5	J
dV/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	20	V/ns
P_D	T_C = 25°C	380	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6 mm (0.063 in.) from case for 10s	300	°C
T_{SOLD}	Plastic body for 10s	260	°C
F_C	Mounting force	30..120/6.7..27	N/lbs
V_{ISOL}	50/60 Hz, RMS t = 1 min	2500	V~
	$I_{ISOL} \le$ 1 mA t = 1 s	3000	V~
Weight		10	g

Symbol	Test Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0 V, I_D = 1mA	1000			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 8mA	3.0		5.5	V
I_{GSS}	V_{GS} = ±30 V, V_{DS} = 0V			± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$			100	µA
	V_{GS} = 0V T_J = 125°C			5	mA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 19A, Note 1			280	mΩ

Features

- Electrically isolated mounting tab
- Double metal process for low gate resistance
- Unclamped Inductive Switching (UIS) rated
- Low package inductance - easy to drive and to protect
- Fast intrinsic diode

Applications

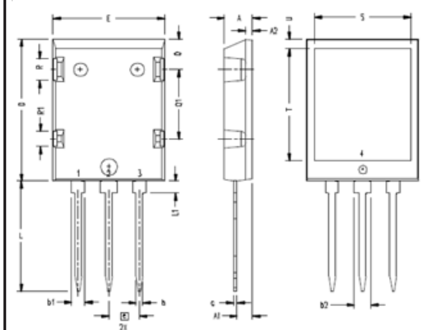
- DC-DC converters
- Switched-mode and resonant-mode power supplies
- DC choppers
- Pulse generation
- Laser drivers

Advantages

- 2500 V~ Electrical isolation
- ISOPLUS 264™ package for clip or spring mounting
- Space savings
- High power density

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 20V, I_D = 19A, Note 1	24	40		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		13.5		nF
C_{oss}			1035		pF
C_{rss}			180		pF
$t_{d(on)}$	**Resistive Switching Times**		25		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 19A		28		ns
$t_{d(off)}$	R_G = 1Ω (External)		57		ns
t_f			15		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 19A		250		nC
Q_{gs}			60		nC
Q_{gd}			105		nC
R_{thJC}				0.33	°C/W
R_{thCS}			0.13		°C/W

ISOPLUS264™ (IXFL) Outline



Note: Bottom heatsink meets

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.190	.205	4.83	5.21
A1	.102	.118	2.59	3.00
A2	.046	.055	1.17	1.40
b	.045	.055	1.14	1.40
b1	.087	.102	2.21	2.59
b2	.111	.126	2.82	3.20
c	.020	.029	0.51	0.74
D	1.020	1.040	25.91	26.42
E	.770	.789	19.56	20.29
e	.215 BSC		5.46 BSC	
L	.780	.820	19.81	20.83
L1	.080	.102	2.03	2.59
Q	.210	.235	5.33	5.97
Q1	.490	.513	12.45	13.03
R	.150	.180	3.81	4.57
R1	.100	.130	2.54	3.30
S	.668	.690	16.97	17.53
T	.801	.821	20.34	20.85
U	.065	.080	1.65	2.03

Ref: IXYS CO 0128

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			38	A
I_{SM}	Repetitive, pulse width limited by T_{JM}			152	A
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = 25A, V_{GS} = 0V			300	ns
Q_{RM}	-di/dt = 100 A/μs		1.4		μC
I_{RM}	V_R = 100 V		9.0		A

Note: 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2 %.

Fig. 1. Output Characteristics @ 25ºC

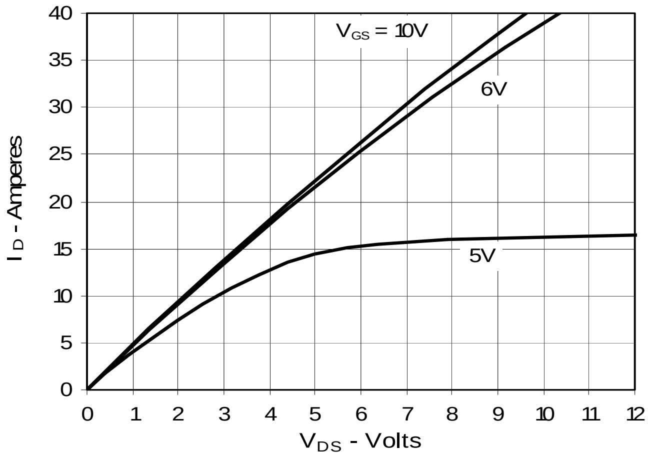


Fig. 2. Extended Output Characteristics @ 25ºC

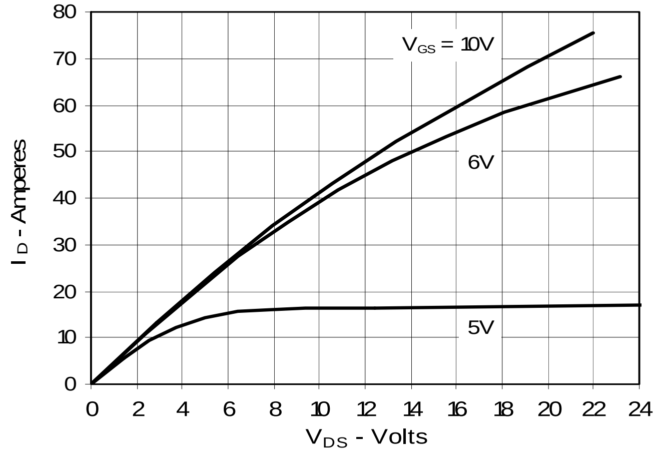


Fig. 3. Output Characteristics @ 125ºC

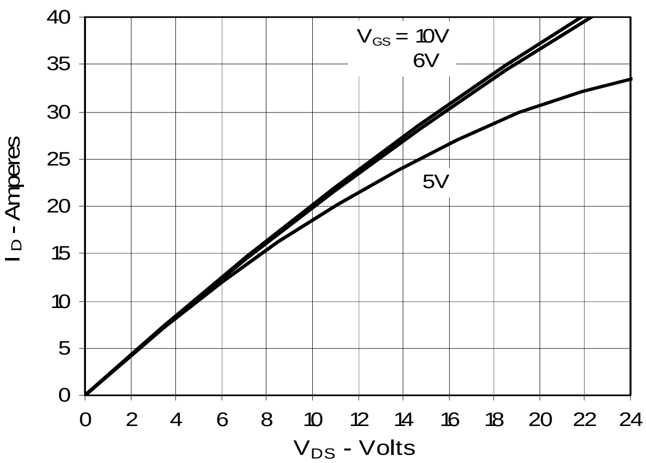


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 19A Value vs. Junction Temperature

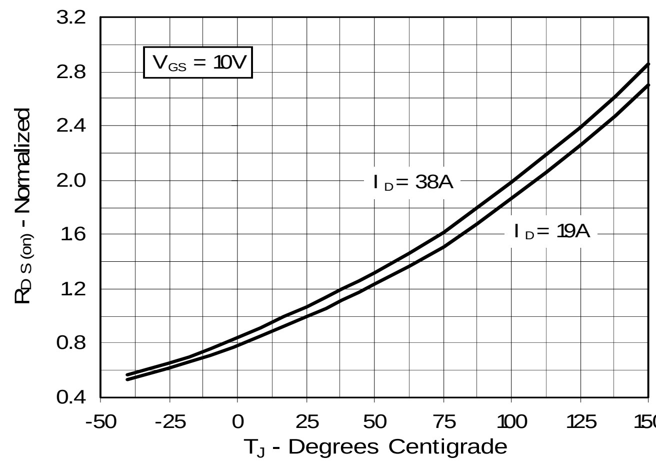


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 19A Value vs. Drain Current

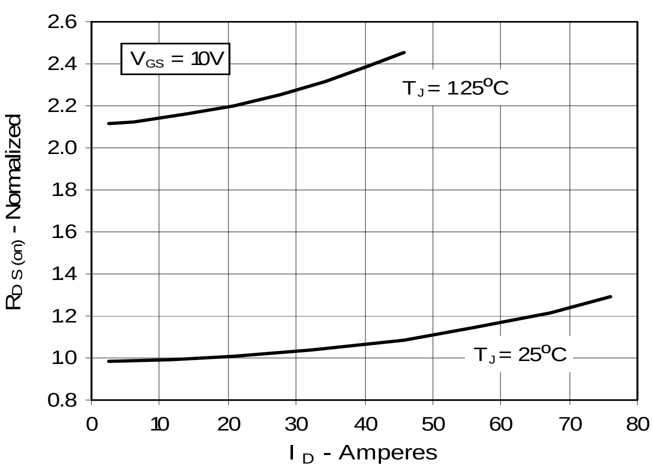


Fig. 6. Drain Current vs. Case Temperature

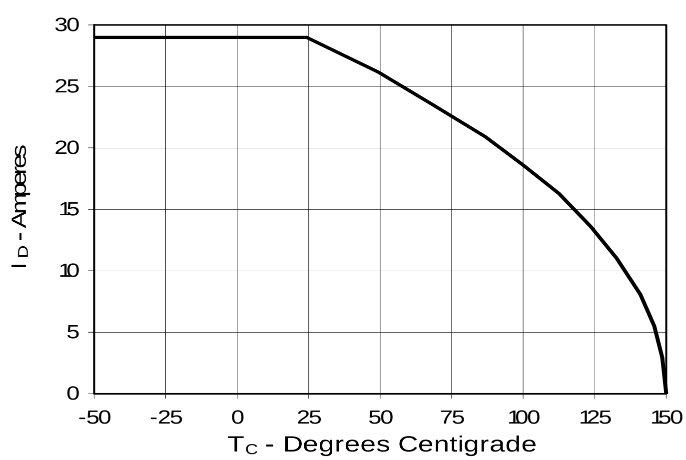


Fig. 7. Input Admittance

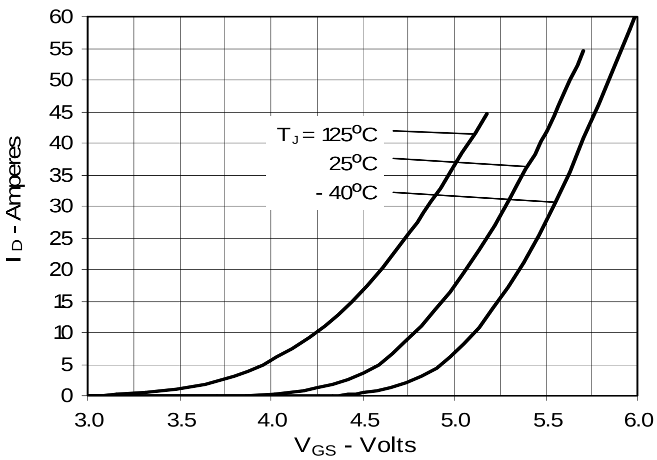


Fig. 8. Transconductance

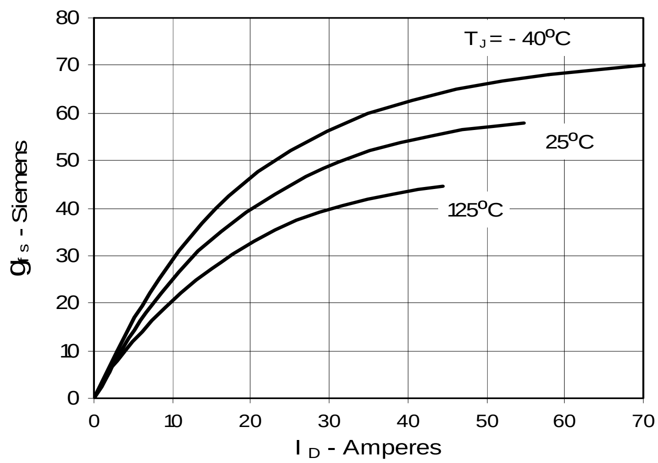


Fig. 9. Source Current vs. Source-To-Drain Voltage

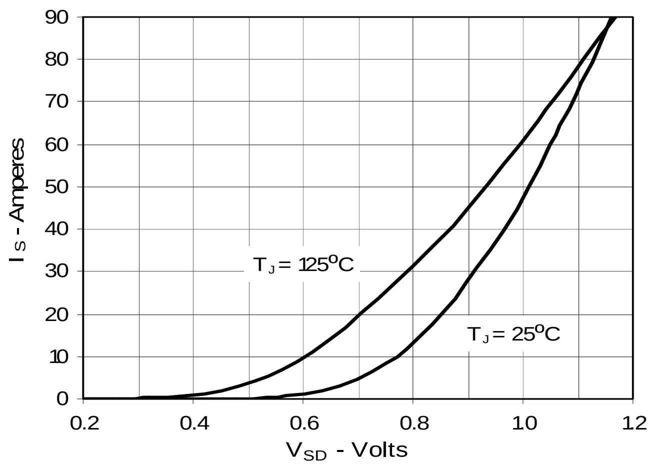


Fig. 10. Gate Charge

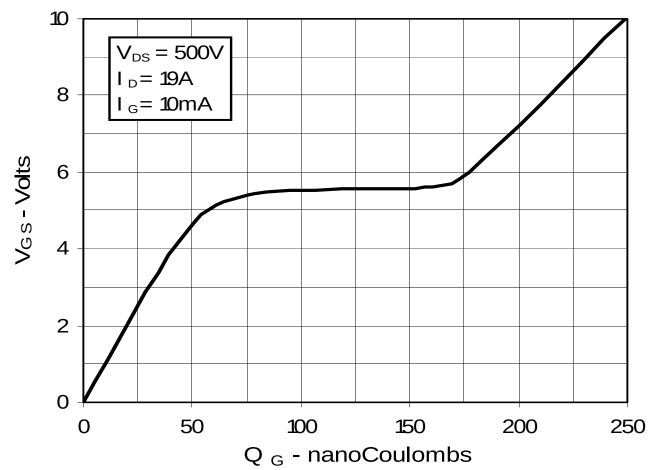


Fig. 11. Capacitance

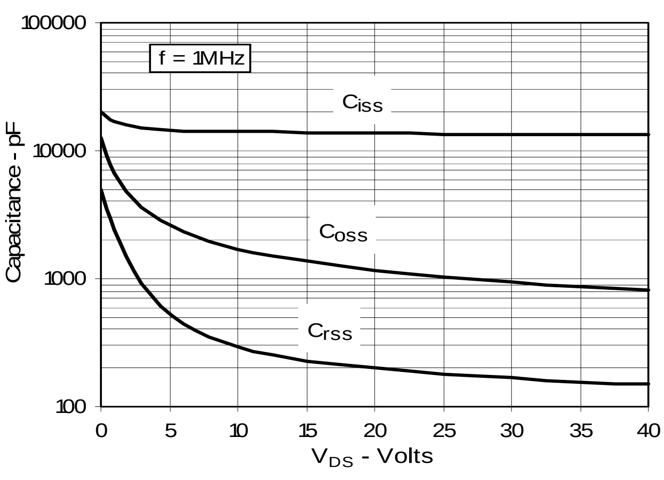


Fig. 12. Maximum Transient Thermal Impedance